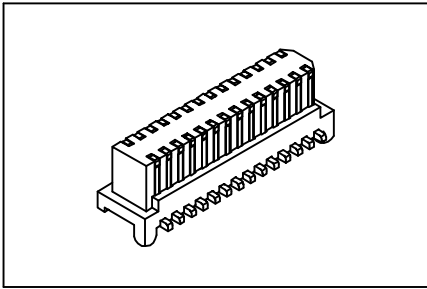


Board To Board 0.8mm(0.0315") Male

GXCON



Material:

Housing: High temperature housing withstands IR and VPR soldering methods.

Contacts: Phosphor Bronze.

Plating: Gold plated over nickel.

Electrical Characteristics:

Current Rating: 0.5 AMP.

Insulator Resistance: 100MΩmin. at DC 500V.

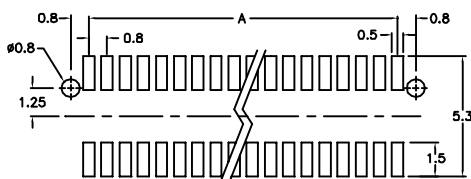
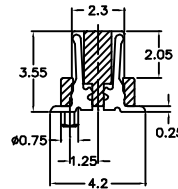
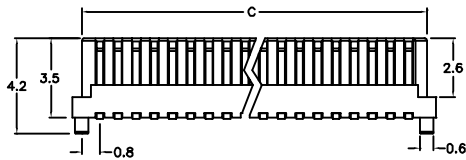
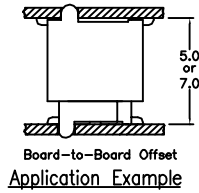
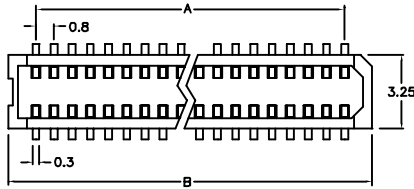
Contact Resistance: 40mΩmax. at DC 100mA.

Operating Temperature: -40°C~+105°C.

Max Processing Temperature: 230°C for 30~60 seconds.

Features:

- * Tube Packing.
- * Ribbon mating type



P.C. Board Layout
(Top View)

Dimension	10 Thru 100
Position	
A±0.05	0.8 X (No. of Positions /2-1)
B±0.15	0.8 X No. of Positions /2+1.6
C±0.08	0.8 X No. of Positions /2+0.75

Ordering information

PH41- 100 1 3 P
 Series No. of Pin Count 1: Gold plated 3: S.M.D. Type. P: With post. N: Without post.